



UT6637

POWER MOSFET

-55A, -35V P-CHANNEL POWER MOSFET

DESCRIPTION

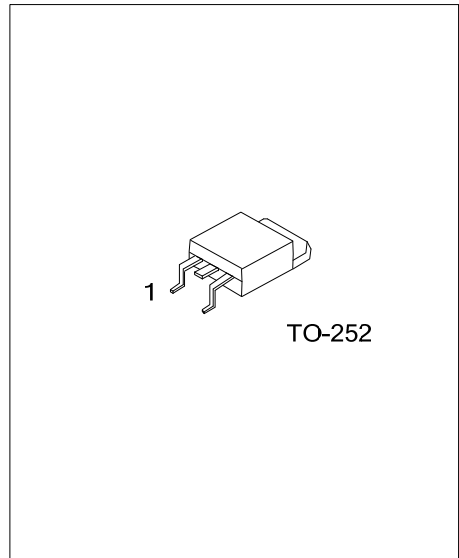
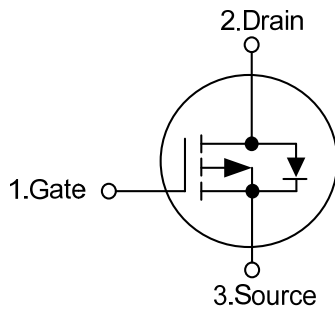
The UTC **UT6637** is P-channel enhancement mode power MOSFET using UTC's advanced technology to provide customers with ideal for low voltage inverter applications.

The UTC **UT6637** is suitable for high efficiency synchronous rectification in SMPS, UPS, hard switched and high frequency circuits.

FEATURES

- * $R_{DS(ON)} \leq 12 \text{ m}\Omega$ @ $V_{GS} = -10\text{V}$, $I_D = -27.5\text{A}$
- * $R_{DS(ON)} \leq 18 \text{ m}\Omega$ @ $V_{GS} = -4.5\text{V}$, $I_D = -27.5\text{A}$
- * High Cell Density Trench Technology
- * High Power and Current Handling Capability

SYMBOL



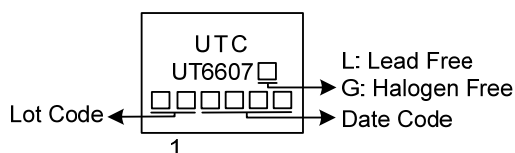
ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UT6637L-TN3-R	UT6637G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>UT6637G-TN3-R</p> <p>(1) Packing Type</p> <p>(2) Package Type</p> <p>(3) Green Package</p>	<p>(1) R: Tape Reel</p> <p>(2) TN3: TO-252</p> <p>(3) G: Halogen Free and Lead Free, L: Lead Free</p>
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MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	-35	V
Gate-Source Voltage		V_{GSS}	± 20	V
Continuous Drain Current	Continuous	I_D	-55	A
Pulsed Drain Current	Pulsed (Note 2)	I_{DM}	-110	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	45	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.5	V/ns
Power Dissipation		P_D	50	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature Range		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L=0.1\text{mH}$, $I_{AS}=-30\text{A}$, $V_{DD}=-10\text{V}$, $R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$.

4. $I_{SD} \leq -30\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$.

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient		θ_{JA}	110	$^\circ\text{C}/\text{W}$
Junction to Case		θ_{JC}	2.5 (Note)	$^\circ\text{C}/\text{W}$

Note: Device mounted on FR-4 substrate P_C board, 2oz copper, with 1inch square copper plate.

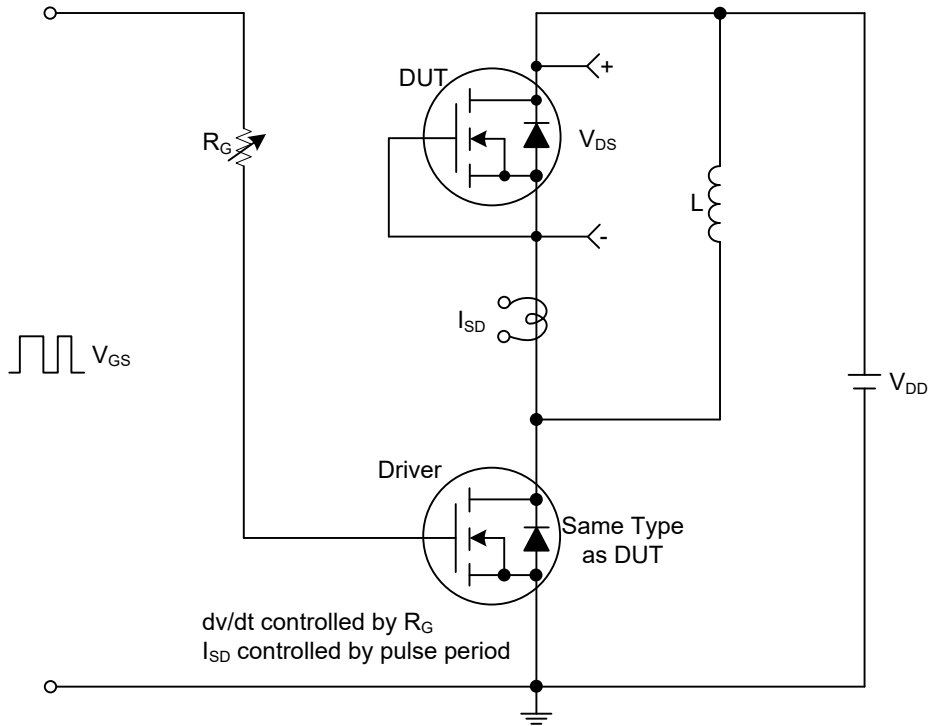
■ ELECTRICAL CHARACTERISTICS ($T_J=25^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-35			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-35\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^{\circ}\text{C}$			-1	μA
Gate-Source Leakage Current	Forward	I_{GSS}			+100	nA
	Reverse				-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.0		-3.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10\text{V}$, $I_D=-27.5\text{A}$			12	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-27.5\text{A}$			18	$\text{m}\Omega$
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1.0\text{MHz}$		3630		pF
Output Capacitance	C_{OSS}			540		pF
Reverse Transfer Capacitance	C_{RSS}			355		pF
SWITCHING PARAMETERS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=-28\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-55\text{A}$ (Note 1, 2)		60		nC
Gate to Source Charge	Q_{GS}			9		nC
Gate to Drain Charge	Q_{GD}			10		nC
Turn-on Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=-15\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-55\text{A}$, $R_G=3\Omega$ (Note 1, 2)		13		ns
Rise Time	t_R			16		ns
Turn-off Delay Time	$t_{D(OFF)}$			67		ns
Fall-Time	t_F			34		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Body-Diode Continuous Current	I_S				-55	A
Maximum Body-Diode Pulsed Current	I_{SM}				-110	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=-55\text{A}$, $V_{GS}=0\text{V}$			-1.4	V
Body Diode Reverse Recovery Time	t_{rr}	$I_S=-30\text{A}$, $V_{GS}=0\text{V}$,		96		ns
Reverse Recovery Charge	Q_{rr}	$di_F/dt=100\text{A}/\mu\text{s}$ (Note 1)		105		ns

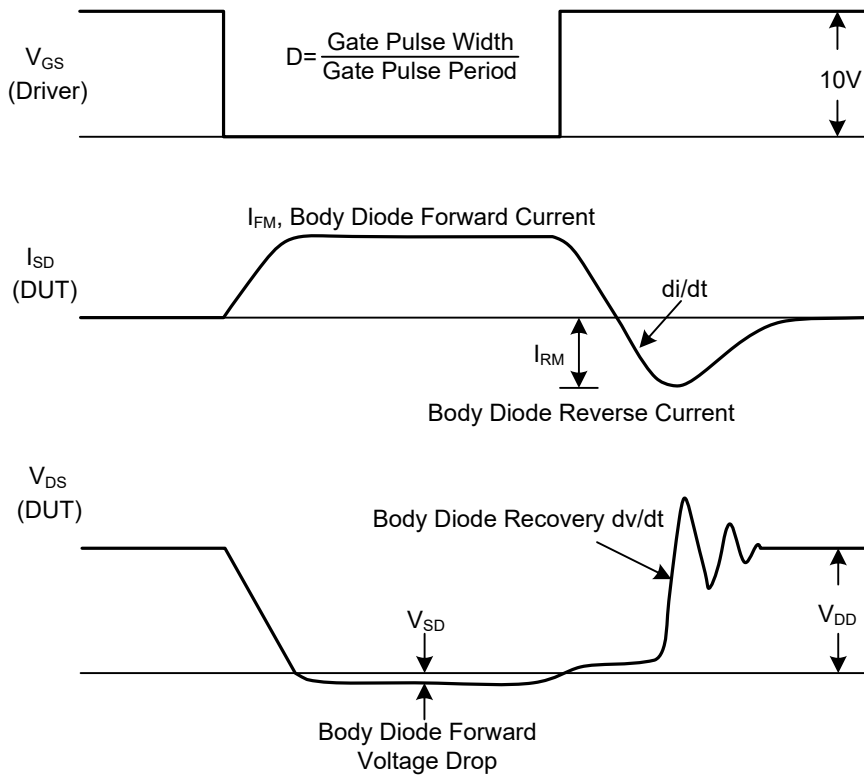
Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS



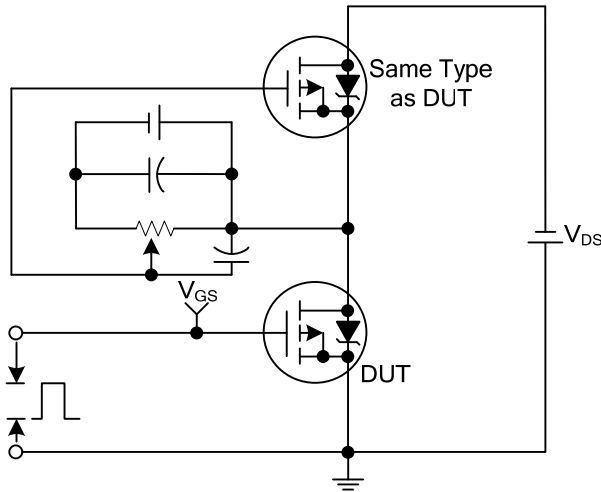
Peak Diode Recovery dv/dt Test Circuit



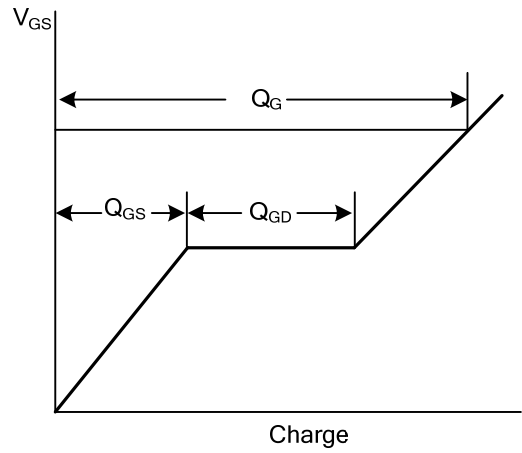
Peak Diode Recovery dv/dt Test Circuit and Waveforms

Peak Diode Recovery dv/dt Waveforms

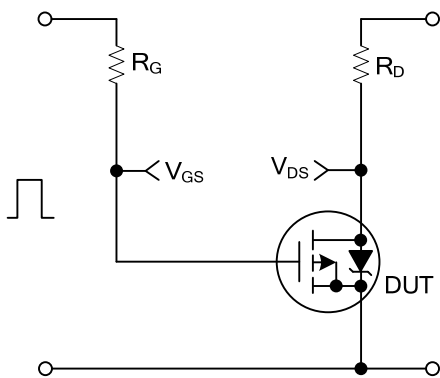
■ TEST CIRCUITS AND WAVEFORMS



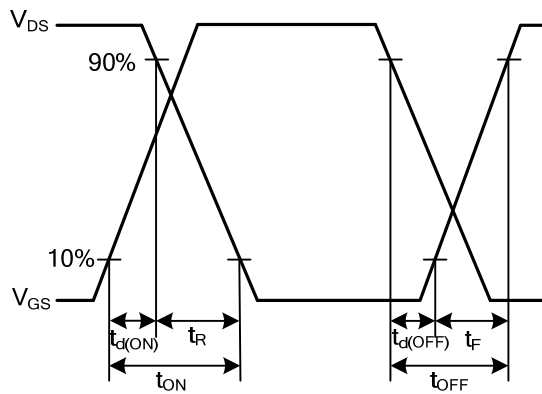
Gate Charge Test Circuit



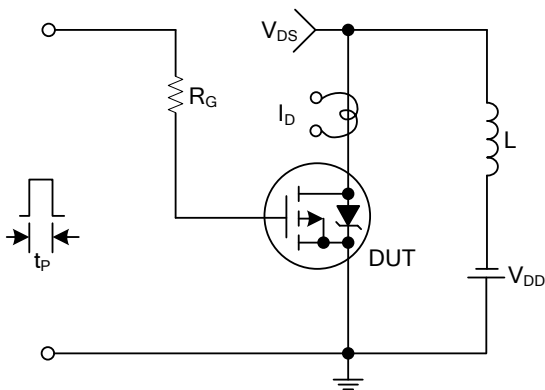
Gate Charge Waveforms



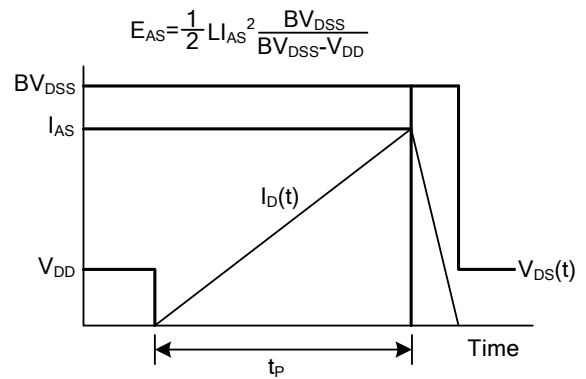
Resistive Switching Test Circuit



Resistive Switching Waveforms

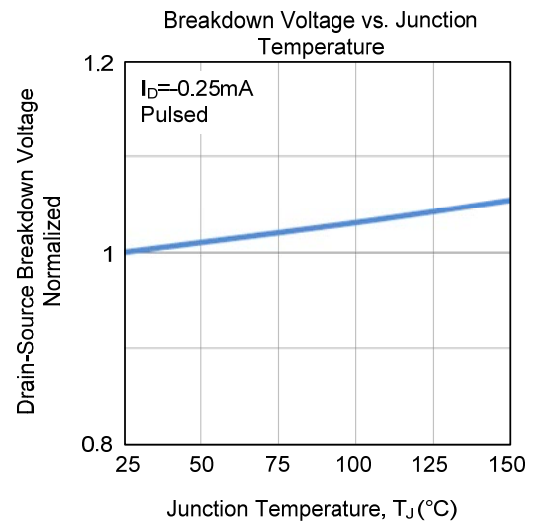
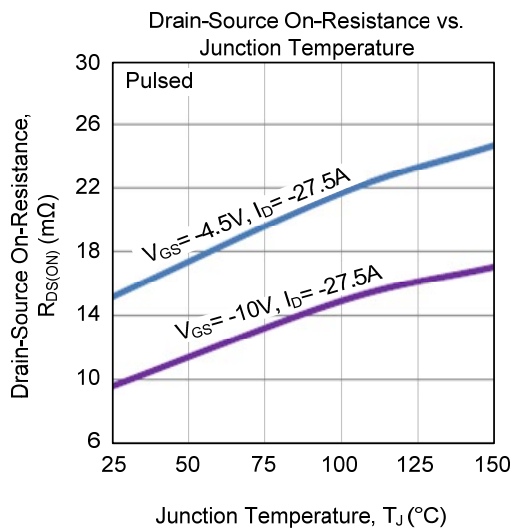
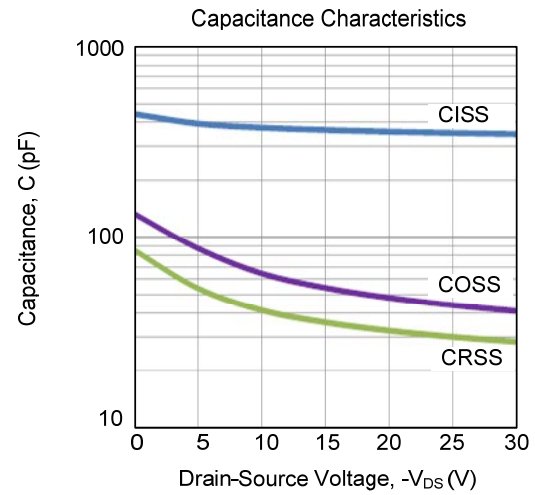
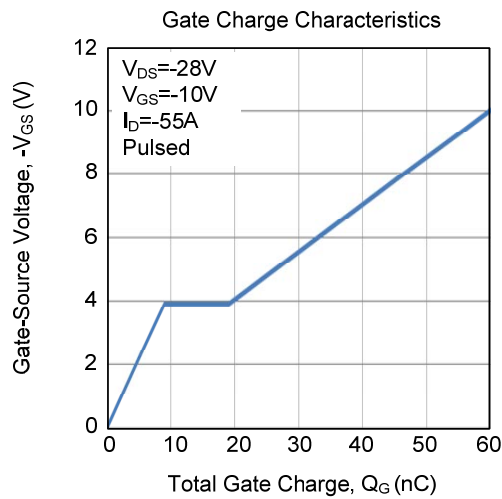
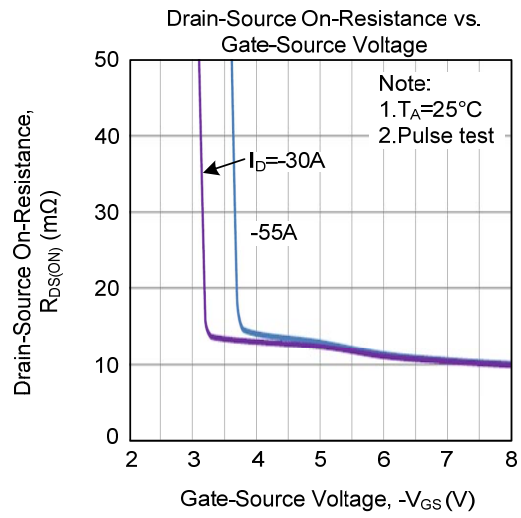
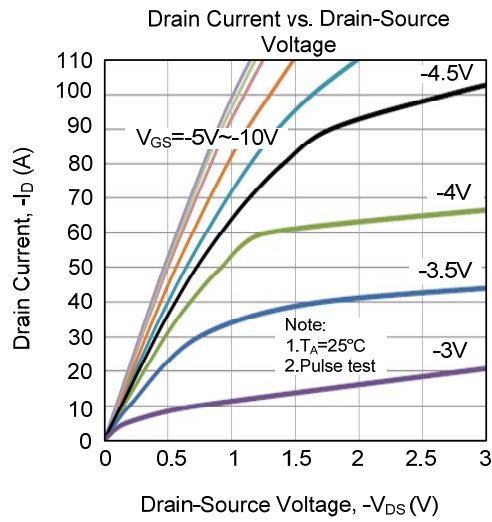


Unclamped Inductive Switching Test Circuit

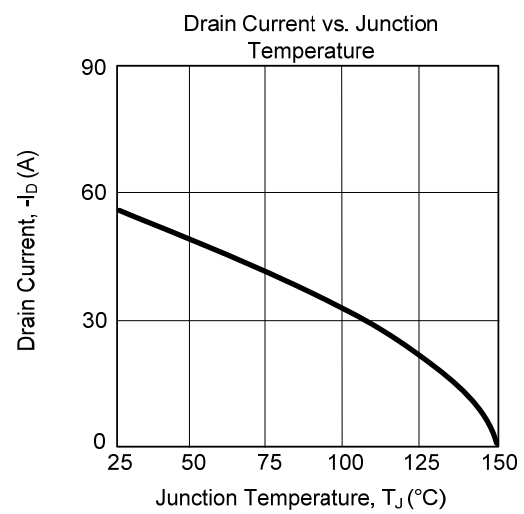
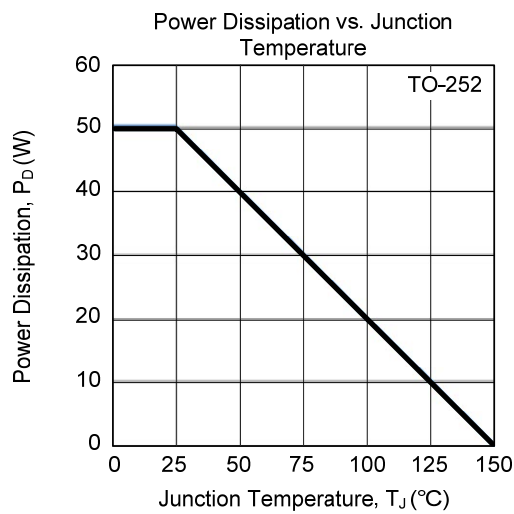
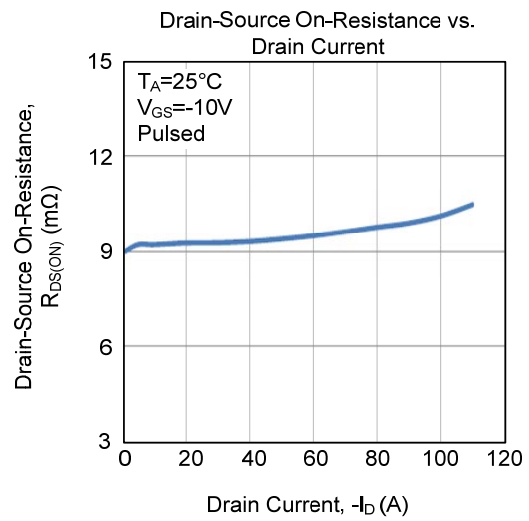
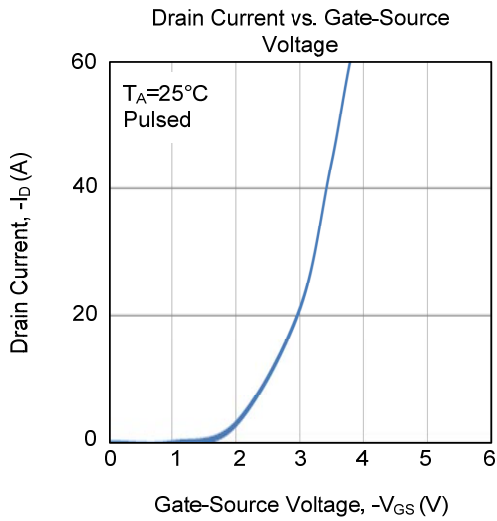
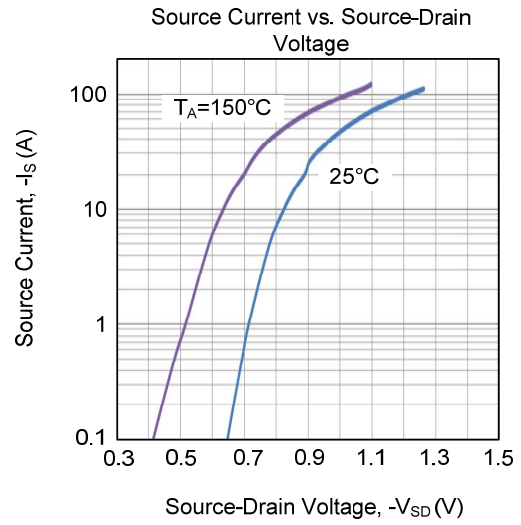
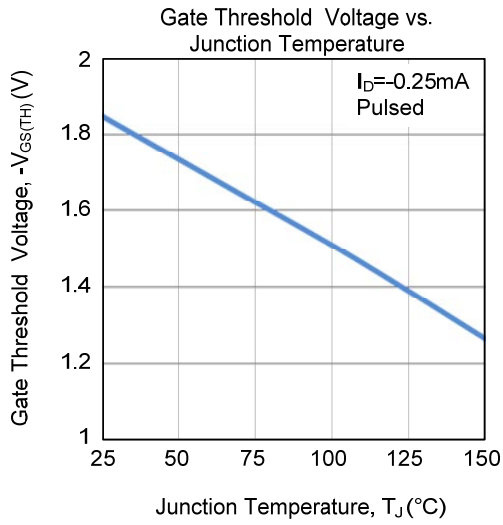


Unclamped Inductive Switching Waveforms

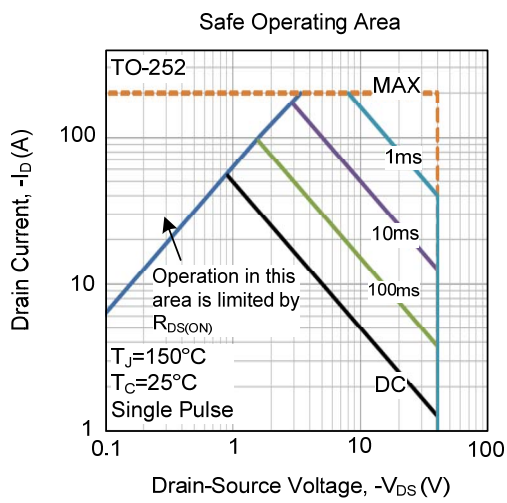
TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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